

1 ABSTRACT OF THE DISCLOSURE

2 We have discovered a method of reducing the effect of material sputtered/etched
3 during the preheating of a substrate. One embodiment of the method pertains to preheating
4 a substrate which includes a metal-containing layer which is to be pattern etched subsequent
5 to preheating. The method includes exposing the substrate to a preheating plasma which
6 produces a deposit or residue during preheating which is more easily etched than said metal-
7 containing layer during the subsequent plasma etching of said metal-containing layer.